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LISTING OF THE CLAIMS (11-19)

Claim 1-10 (canceled).

Claim 11 (new): A packaged semiconductor device for mounting on a surface, said package comprising:

a leadframe having a first portion and a second portion wherein said first portion is formed in the shape of a cup;

a semiconductor die having a first surface and a second surface, disposed inside said first portion, wherein said first surface is attached to said first portion;

a plurality of leads formed in said second portion, wherein each of said leads has a mounting surface that is coplanar with said second surface of said die; and (2)

a capsule partially enclosing said leadframe and said die, exposing the entire mounting surface of each of said leads and the entire second surface of said die. (1)

Claim 12 (new): The packaged semiconductor device of Claim 11, wherein said semiconductor die is attached to said first portion of said leadframe by a conductive cement.

Claim 13 (new): The packaged semiconductor device of Claim 12, wherein said conductive cement is a conductive epoxy.

Claim 14 (new): The packaged semiconductor device of Claim 13, wherein said capsule comprises a thermal set plastic.

Claim 15 (new): The packaged semiconductor device of Claim 11, wherein said semiconductor die comprises a MOSFET.

Claim 16 (new): The packaged semiconductor device of Claim 15, wherein said MOSFET is a vertical MOSFET.

Claim 17 (new): The packaged semiconductor device of Claim 15, wherein said first surface comprises a drain terminal.

Claim 18 (new): The packaged semiconductor device of Claim 17, wherein said second surface comprises a gate terminal and a source terminal.

Claim 19 (new): The packaged semiconductor device of Claim 11, wherein said semiconductor die comprises an integrated circuit.

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